

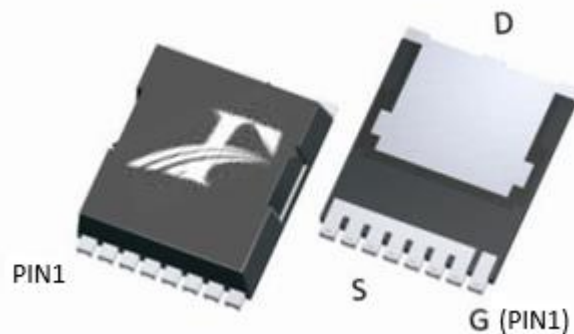
主要参数 MAIN CHARACTERISTICS

ID	300 A
VDSS	100 V
Rdson-typ (@Vgs=10V)	1.60 mΩ
Qg-typ	224 nC

用途 APPLICATIONS

电机驱动	Motor Drive
电池管理系统	Battery Management System
电动车控制器	Electric vehicle controller
高频开关电源	High efficiency switch mode power supplies
同步整流	Synchronus Rectification

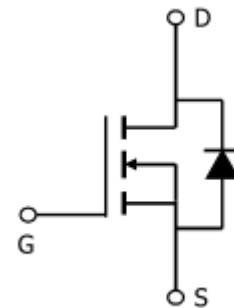
封装形式 Package



产品特性 FEATURES

低栅极电荷	Low gate charge
低 Crss (典型值 328 pF)	Low Crss (typical 328 pF)
开关速度快	Fast switching
100%经过热阻测试	100% DVDS tested
100%经过雪崩测试	100% avalanche tested
100%经过 Rg 测试	100% Rg tested
符合 RoHS 标准	ROHS compliant
SGT 工艺	SGT technology

等效电路 Equivalent Circuit



绝对最大额定值 ABSOLUTE RATINGS (Tc=25°C)

项目 Parameter	符号 Symbol	数值 Value	单位 Unit
		FHL300N1F2A	
最高漏极-源极直流电压 Drain-Source Voltage	VDS	100	V
连续漏极电流* Drain Current -continuous *	Id(Tc =25°C),Silicon Limited	300	A
	Id(Tc =100°C),Silicon Limited	185	A
最大脉冲漏极电流 (注 1) Drain Current – pulse (note 1)	IDM	1200	A
最高栅源电压 Gate-Source Voltage	VGS	±20	V
单脉冲雪崩能量 (注 2) Single Pulsed Avalanche Energy (note 2)	EAS	612.5	mJ
雪崩电流 (注 1) Avalanche Current (note 1)	IAS	35	A
二极管反向恢复最大电压变化速率 (注 3) Peak Diode Recovery dv/dt (note 3)	dv/dt	5.0	V/ns
耗散功率 Power Dissipation	PD (TC=25°C)	290.7	W
	-Derate above 25°C	2.32	W/°C
最高结温及存储温度 Operating and Storage Temperature Range	TJ, TSTG	150,-55~+150	°C
引线最高焊接温度 Maximum Lead Temperature for Soldering Purposes	TL	260	°C

*漏极电流由最高结温限制

*Drain current limited by maximum junction temperature

电特性 ELECTRICAL CHARACTERISTICS

项目 Parameter	符号 Symbol	测试条件 Tests conditions	最小 Min	典型 Typ	最大 Max	单位 Units
关态特性 Off –Characteristics						
漏-源击穿电压 Drain-Source Voltage	BVDSS	ID=250μA, VGS=0V	100	108	-	V
击穿电压温度特性 Breakdown Voltage Temperature Coefficient	ΔBVDSS/ΔTJ	ID=250μA, referenced to 25°C	-	0.1	-	V/°C
零栅压下漏极漏电流 Zero Gate Voltage Drain Current	IDSS	VDS=100V, VGS=0V, Tc=25°C	-	-	1	μA
		VDS=80V, Tc=125°C	-	-	100	μA
栅极体漏电流 Gate-body leakage current	IGSS (F/R)	VDS=0V, VGS =±20V	-	-	±100	nA
通态特性 On-Characteristics						
阈值电压 Gate Threshold Voltage	VGS(th)	VDS = VGS , ID=250μA	2.0	3.0	4.0	V
静态导通电阻 Static Drain-Source On-Resistance	RDS(ON)	VGS =10V , ID=50A	-	1.60	2.0	mΩ
动态特性 Dynamic Characteristics						
栅电阻 Gate Resistance	Rg	f=1.0MHz, VDS OPEN	-	0.6	-	Ω
输入电容 Input capacitance	Ciss	VDS=50V, VGS =0V, f=1.0MHz	-	11260	-	pF
输出电容 Output capacitance	Coss		-	1715	-	
反向传输电容 Reverse transfer capacitance	Crss		-	328	-	
开关特性 Switching Characteristics						
延迟时间 Turn-On delay time	td(on)	VDS=50V, ID=50A, RG=3Ω VGS =10V (note 4, 5)	-	34	-	ns
上升时间 Turn-On rise time	tr		-	26	-	ns
延迟时间 Turn-Off delay time	td(off)		-	78	-	ns
下降时间 Turn-Off Fall time	tf		-	30	-	ns
栅极电荷总量 Total Gate Charge	Qg	VDS =50V , ID=50A , VGS =10V (note 4, 5)	-	224	-	nC
栅-源电荷 Gate-Source charge	Qgs		-	80	-	nC
栅-漏电荷 Gate-Drain charge	Qgd		-	38	-	nC
漏-源二极管特性及最大额定值 Drain-Source Diode Characteristics and Maximum Ratings						
正向最大连续电流 Maximum Continuous Drain-Source Diode Forward Current		IS	-	-	300	A
正向最大脉冲电流 Maximum Pulsed Drain-Source Diode Forward Current		ISM	-	-	1200	A
正向压降 Drain-Source Diode Forward Voltage	VSD	VGS=0V, IS=50A	-	-	1.3	V
反向恢复时间 Reverse recovery time	trr	VGS=0V, IS=50A ,dIF/dt=100A/μs (note 4)	-	100	-	ns
反向恢复电荷 Reverse recovery charge	Qrr		-	280	-	nC

热特性 THERMAL CHARACTERISTIC

项目 Parameter	符号 Symbol	FHL300N1F2A	单位 Unit
结到管壳的热阻 Thermal Resistance, Junction to Case	Rth(j-c)	0.43	°C/W
结到环境的热阻 Thermal Resistance, Junction to Ambient	Rth(j-A)	62.5	°C/W

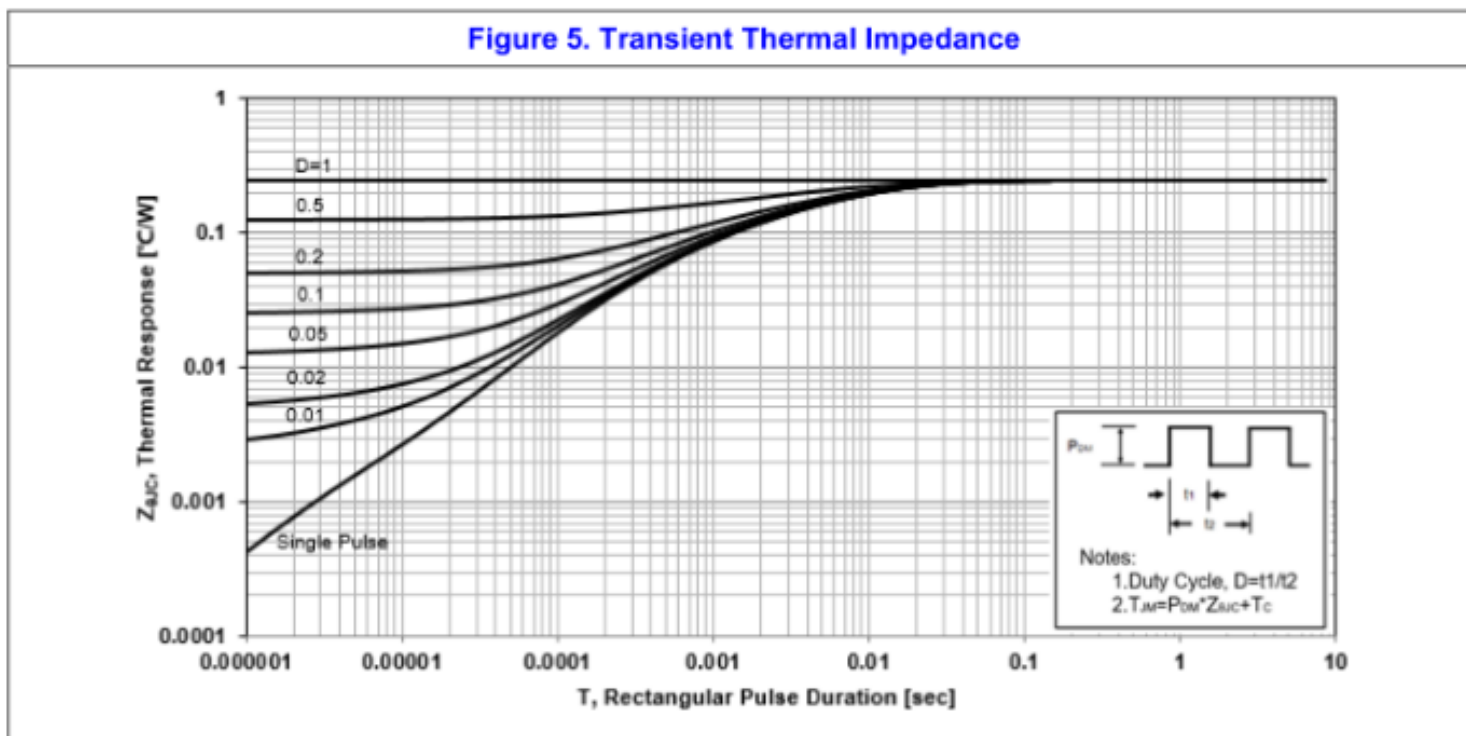
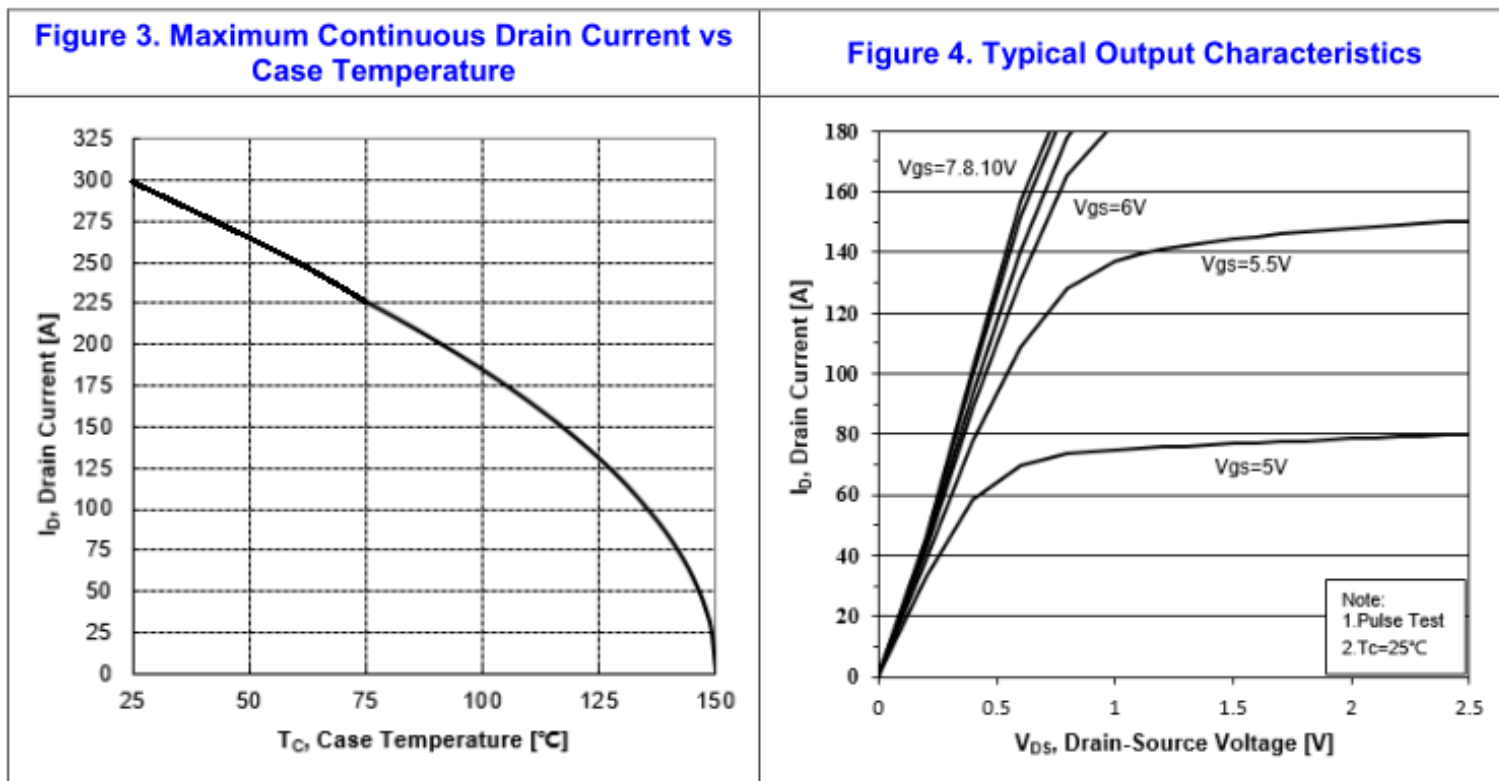
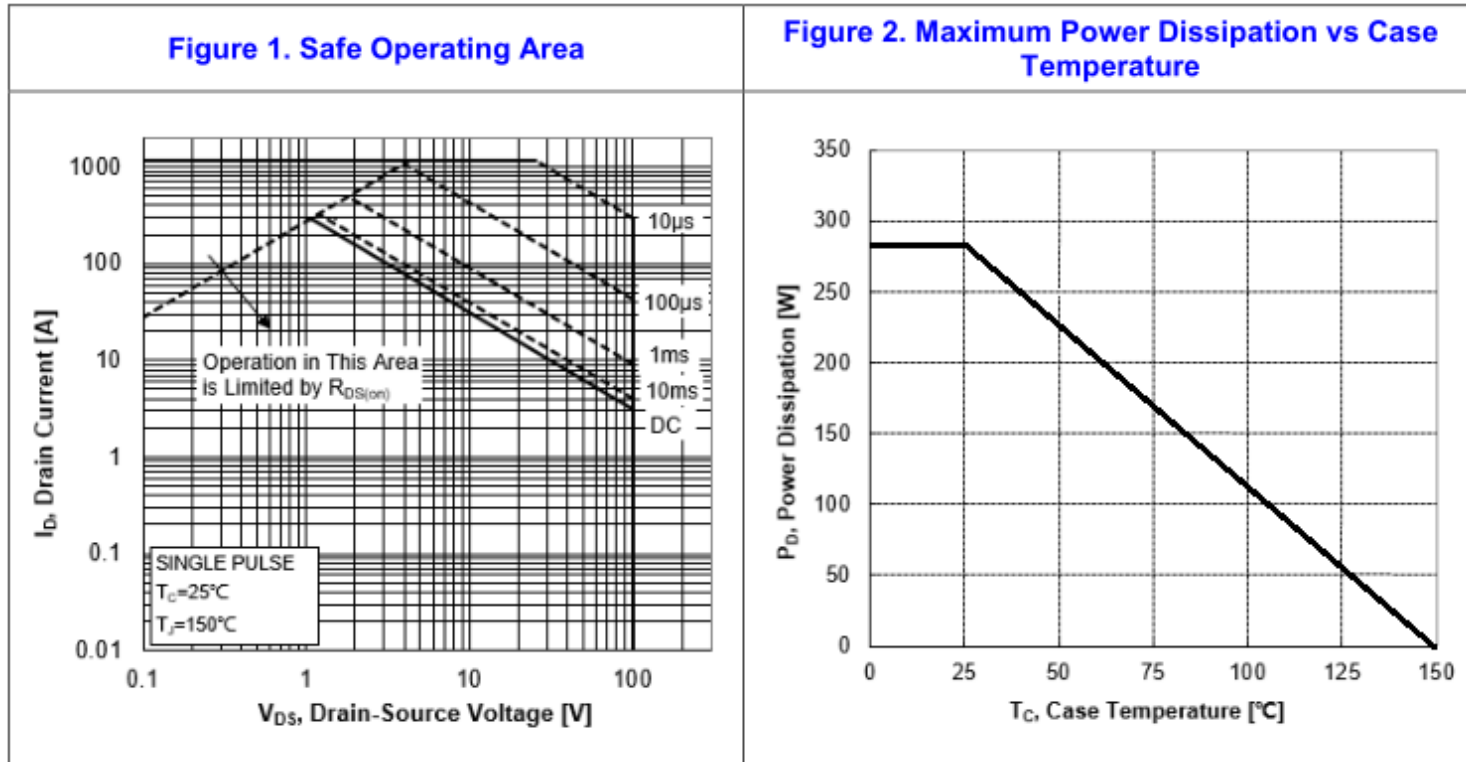
注释:

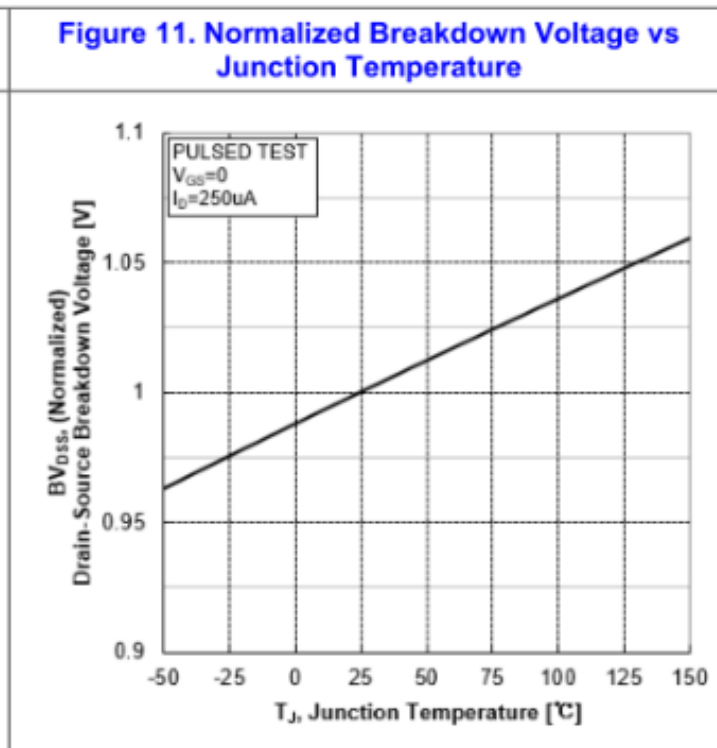
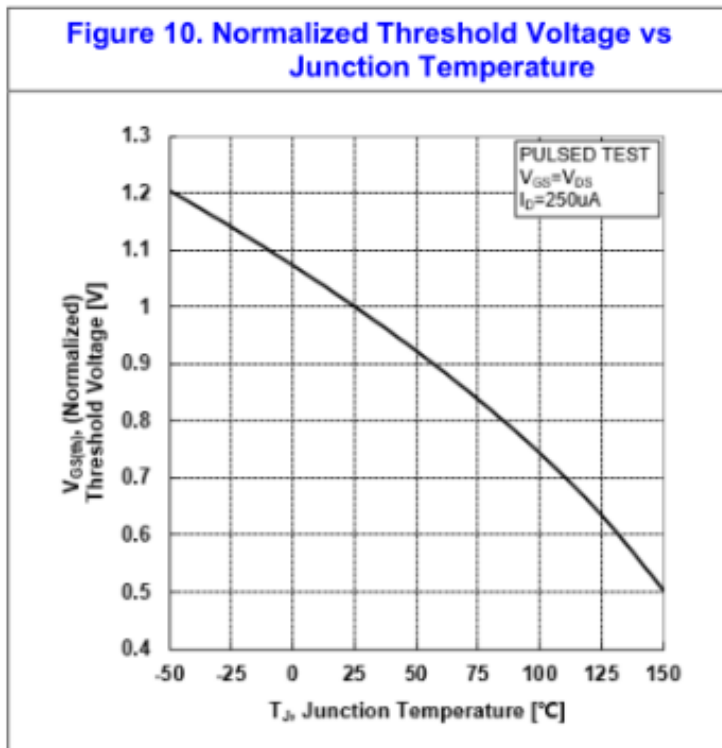
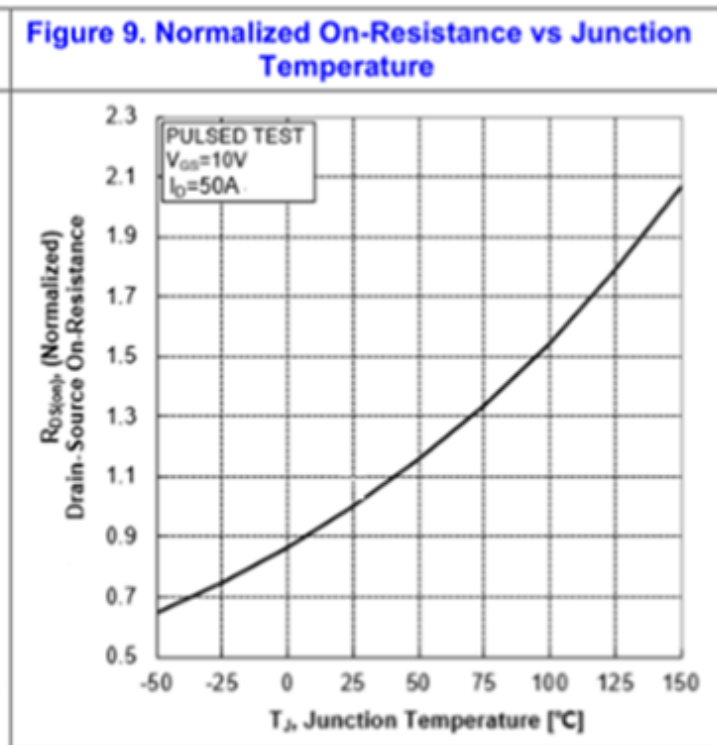
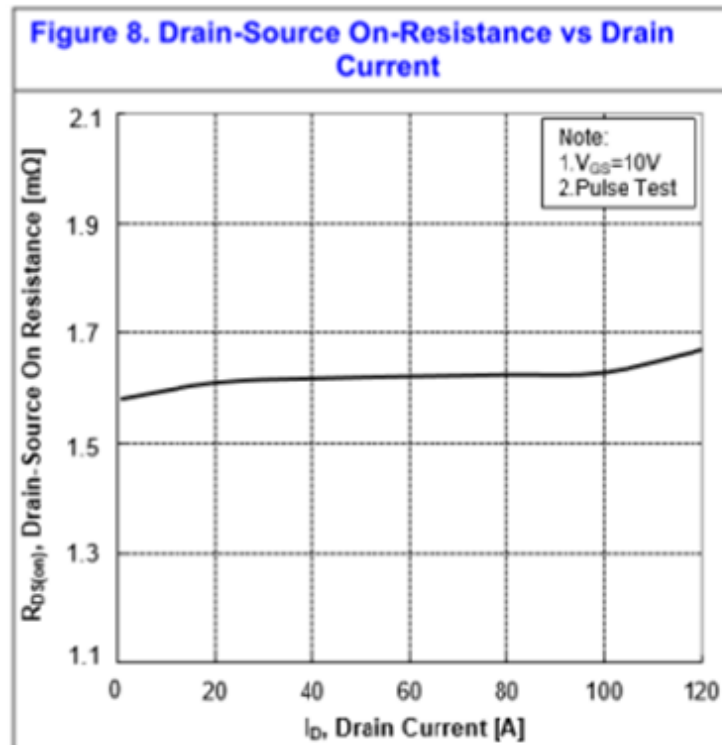
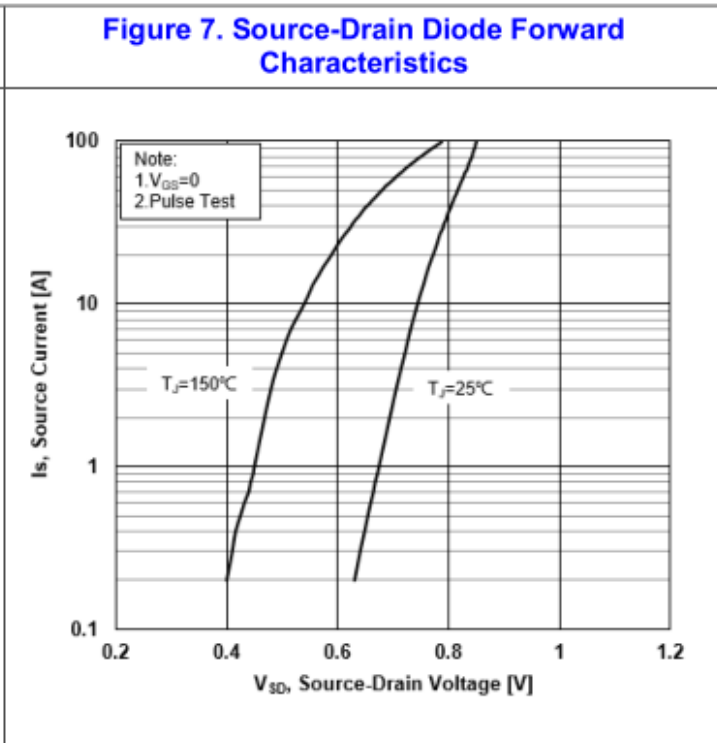
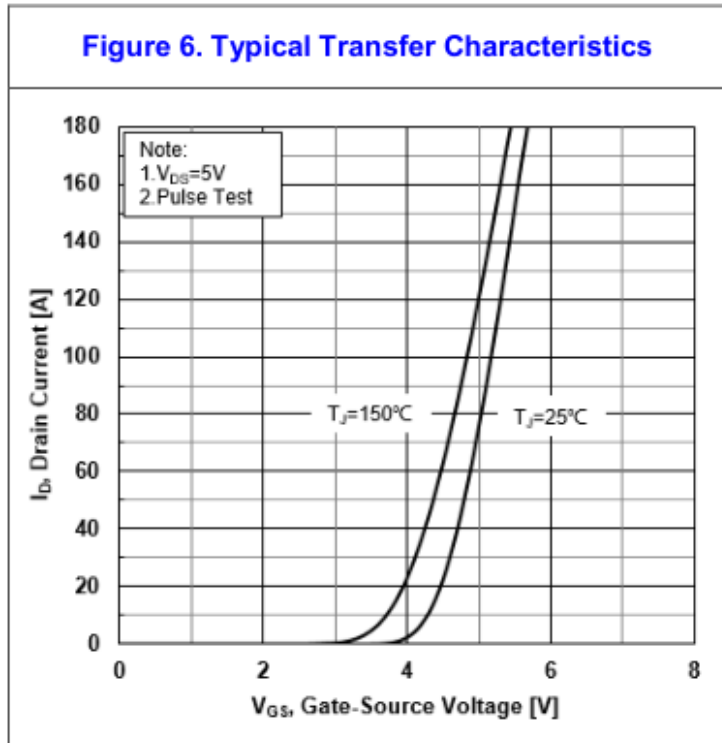
- 1: 脉冲宽度由最高结温限制
- 2: L=1mH, I_{AS}=35A, V_{DD}=50V, R_G=25 Ω, 起始结温 T_J=25°C
- 3: I_{SD} ≤300A, di/dt ≤100A/μs, V_{DD} ≤BV_{DSS}, 起始结温 T_J=25°C
- 4: 脉冲测试: 脉冲宽度 ≤300μs, 占空比 ≤2%
- 5: 基本与工作温度无关

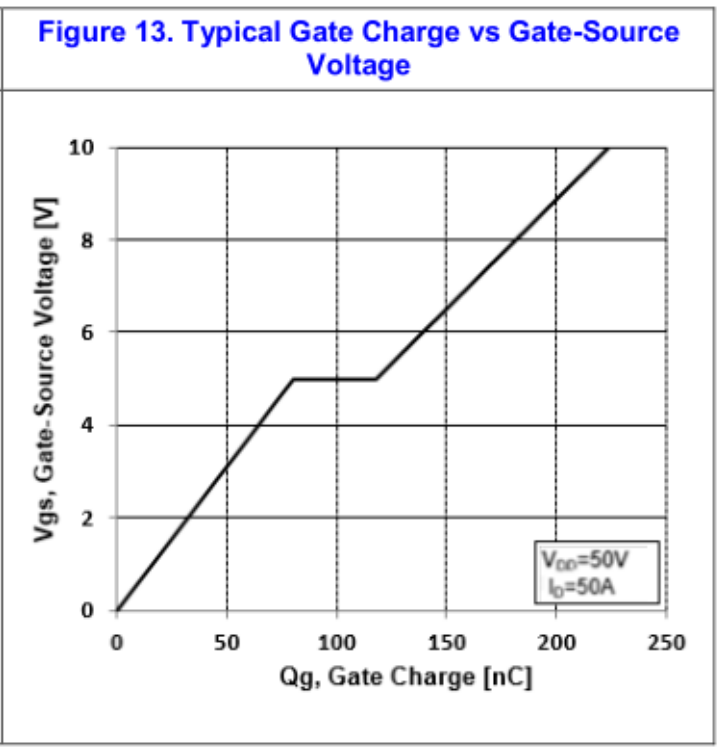
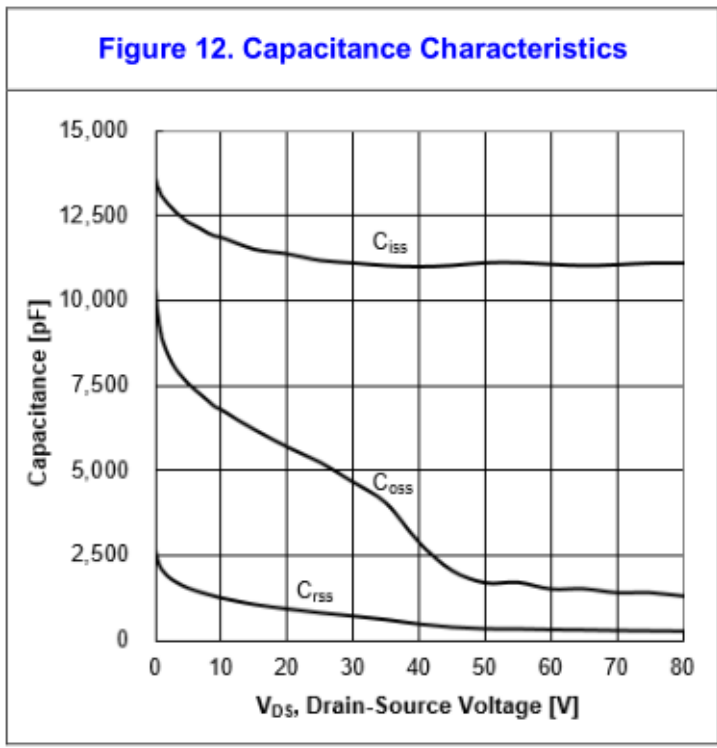
Notes:

- 1: Pulse width limited by maximum junction temperature
- 2: L=1mH, I_{AS}=35A, V_{DD}=50V, R_G=25 Ω, Starting T_J=25°C
- 3: I_{SD} ≤300A, di/dt ≤100A/μs, V_{DD} ≤BV_{DSS}, Starting T_J=25°C
- 4: Pulse Test: Pulse Width ≤300μs, Duty Cycle ≤2%
- 5: Essentially independent of operating temperature

特性曲线 Typical Characteristics

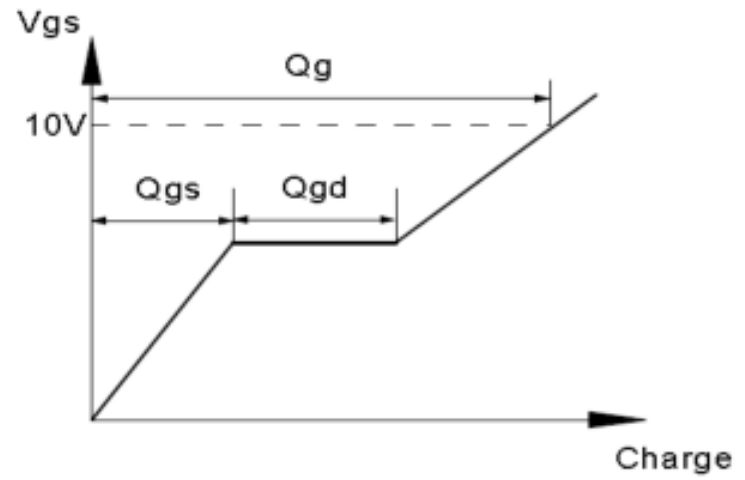
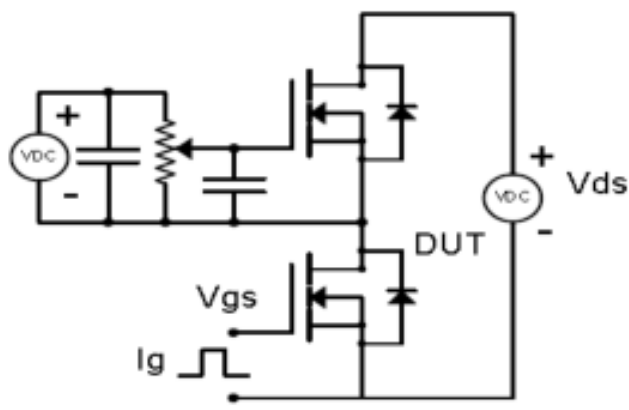




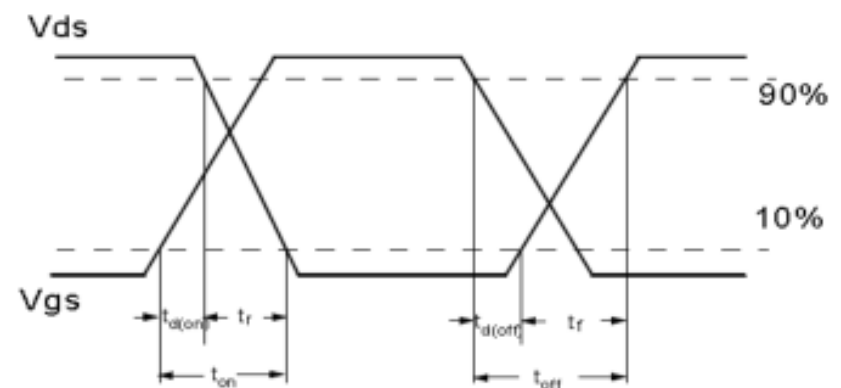
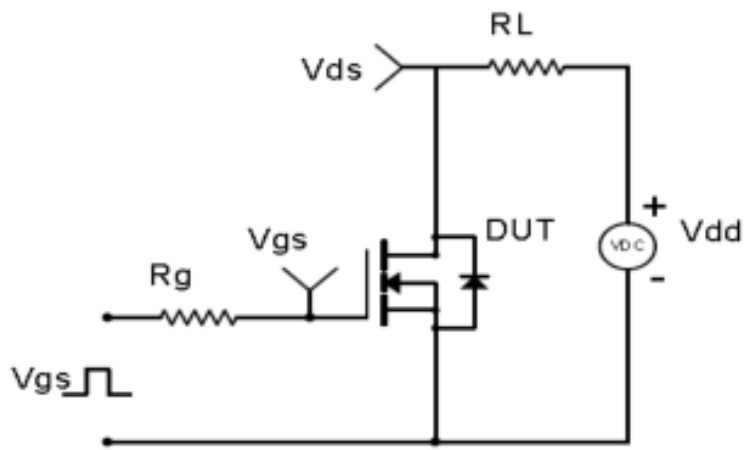


Test Circuit & Waveform

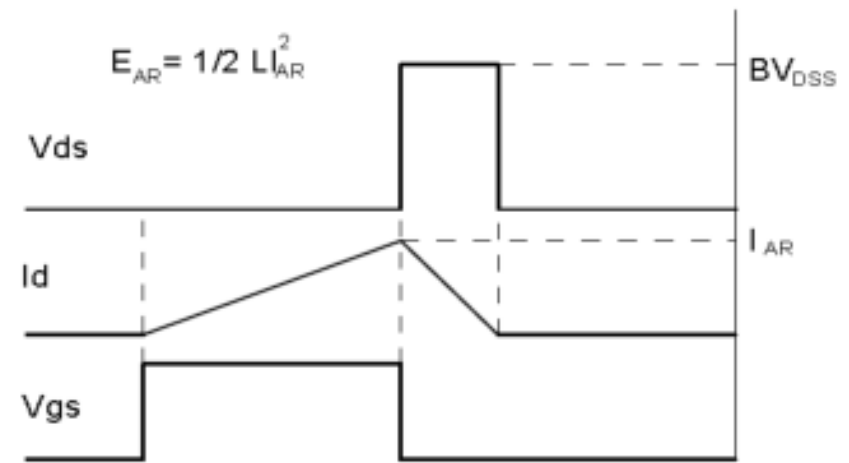
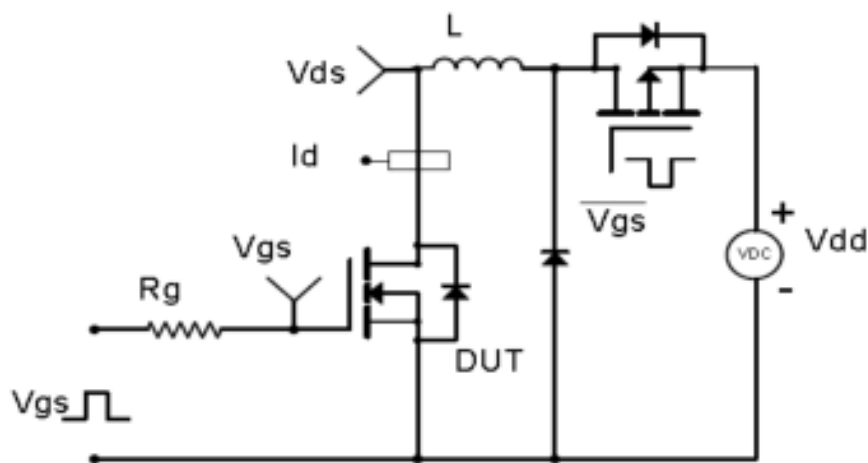
Gate Charge Test Circuit & Waveform



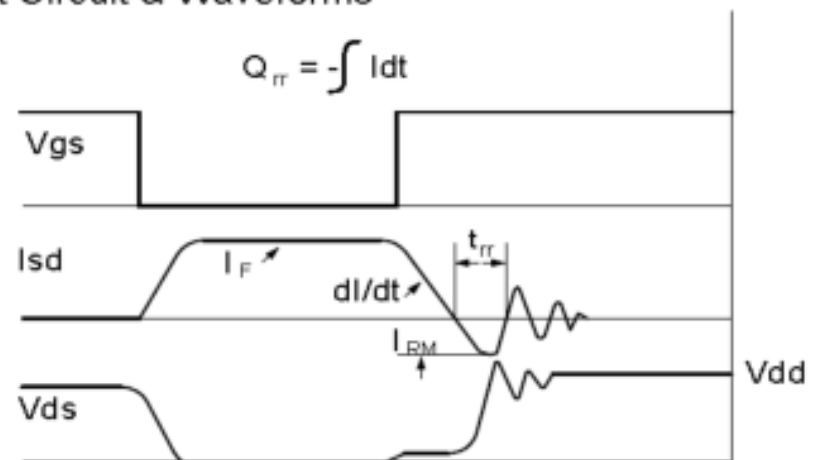
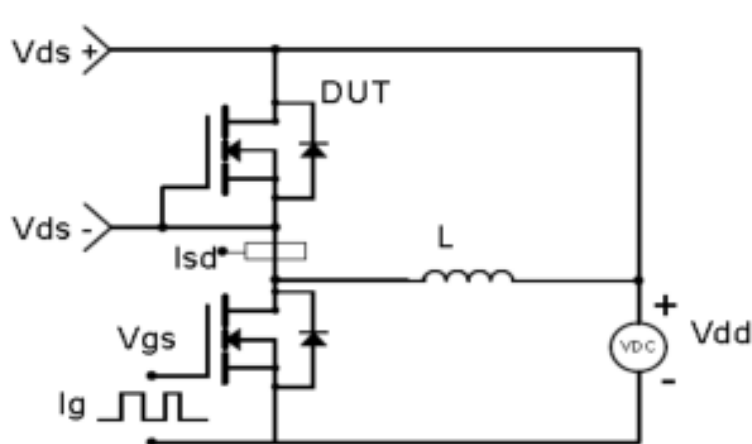
Resistive Switching Test Circuit & Waveforms



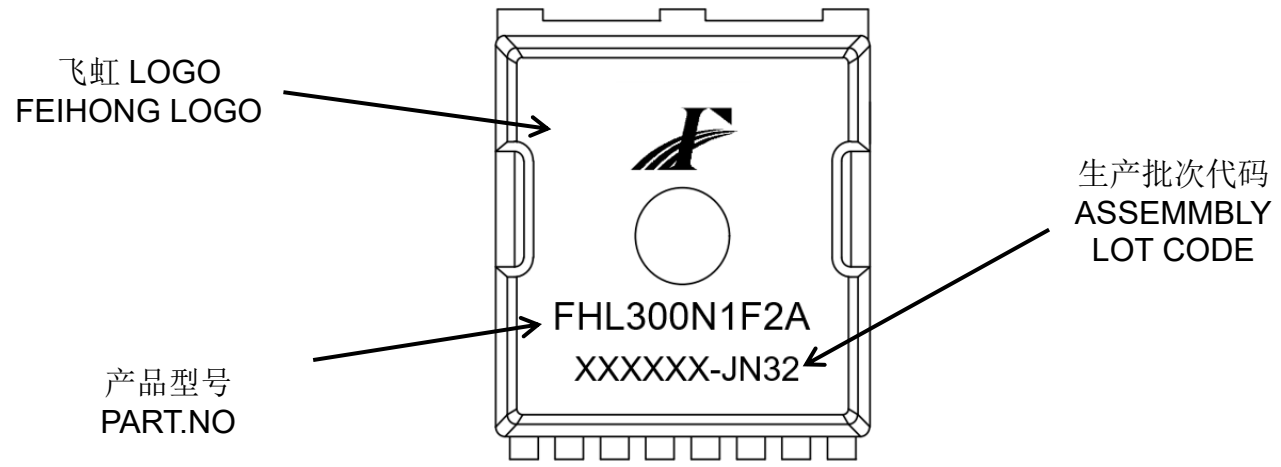
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



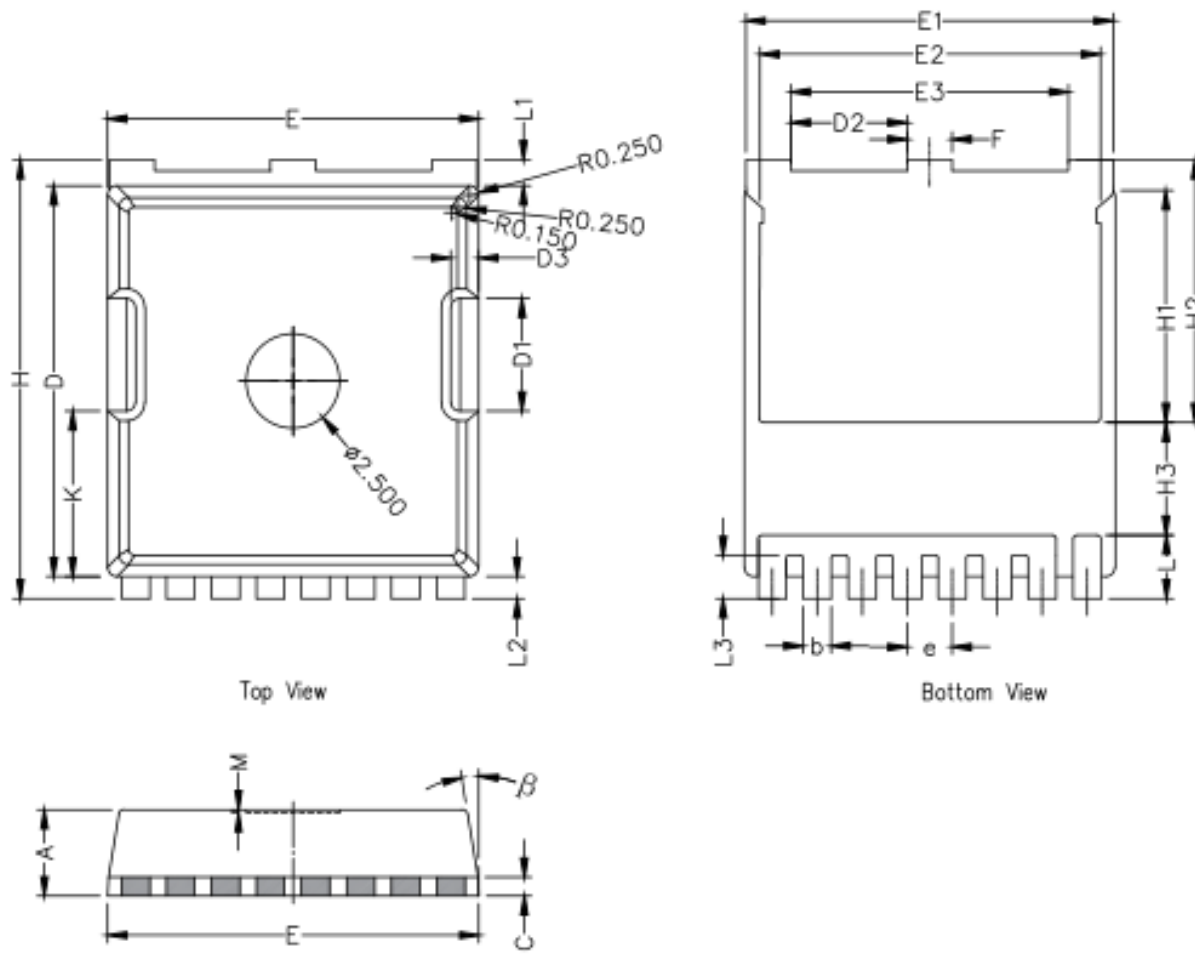
印记 Marking:



外形尺寸:

Package Dimension:

TOLL8



Symbols	Millimeters		
	MIN.	NOM.	MAX.
A	2.20	2.30	2.40
b	0.65	0.75	0.85
C	0.508 REF		
D	10.25	10.40	10.55
D1	2.85	3.00	3.15
D2	2.95	3.10	3.25
D3	0.75 REF		
E	9.75	9.90	10.05
E1	9.65	9.80	9.95
E2	8.95	9.10	9.25
E3	7.25	7.40	7.55
e	1.20 BSC		
F	1.05	1.20	1.35
H	11.55	11.70	11.85
H1	6.03	6.18	6.33
H2	6.85	7.00	7.15
H3	3.00 BSC		
L	1.55	1.70	1.85
L1	0.55	0.70	0.85
L2	0.45	0.60	0.75
L3	1.00	1.15	1.30
M	0.08 REF		
β	8°	10°	12°
K	4.25	4.40	4.55